MDOB128064V2V-YI	128 x 64	OLED Module
Specification		
Version: 3	Date: 22/03/2019	
Revision		

1	31/05/2018	First release
2	27/11/2018	Modify Static electricity test Content of Test
3	21/03/2019	Modify Application recommendations & DC Electrical Characteristics

Display Features		RoHS compliant
Resolution	128 x 64	
Appearance	Yellow on Black	
Logic Voltage	3V	
Interface	I2C	
Module Size	27.3 x 27.3 x 2.37mm	
Operating Temperature	-40°C ~ +80°C	Box Quantity / Weight / Display
Construction	COB	--- / ---

* - For full design functionality, please use this specification in conjunction with the SSD1306BZ specification. (Provided Separately)

Display Accessories	
Part Number	Description

Optional Variants	
Appearance	Voltage

General Specification

The Features is described as follow:

- Module dimension: 27.3 x 27.3 x 2.37 mm
- Active area: 21.74 x 10.86 mm
- Dot Matrix: 128 × 64
- Dot size: 0.148 × 0.148 mm
- Dot pitch: 0.17 × 0.17 mm
- Display Mode：Passive Matrix
- Duty: 1/64 Duty
- Display Color: Monochrome (Yellow)
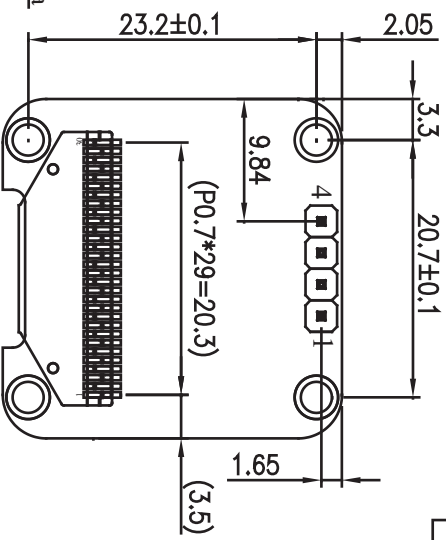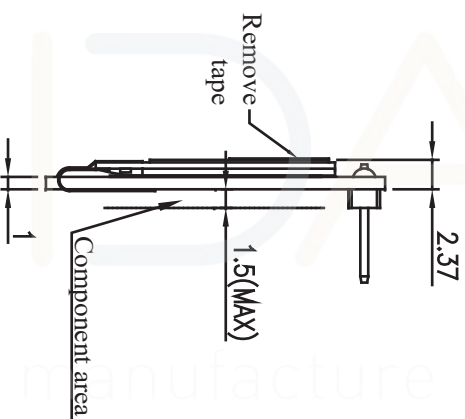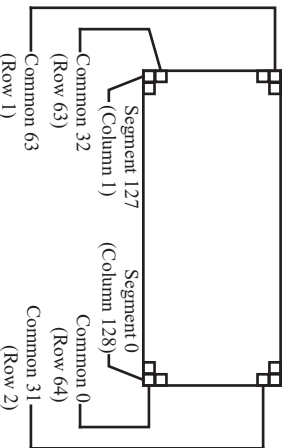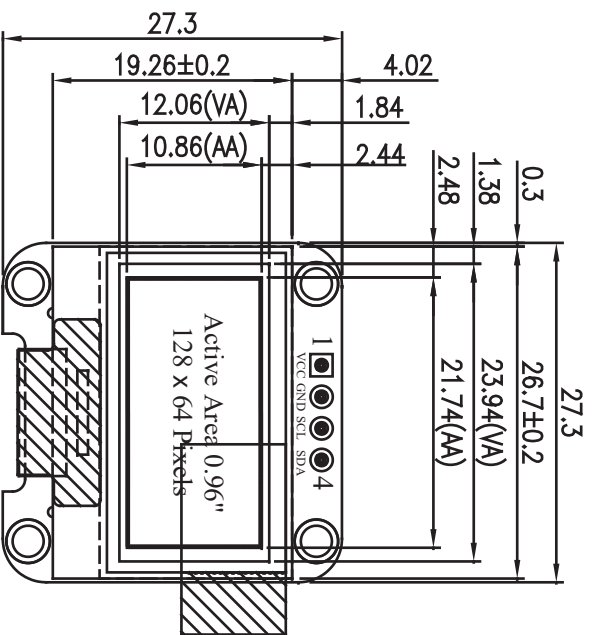- IC: SSD1306BZ
- Interface: I2C
- SIZE: 0.96 inch

Interface Pin Function

No.	Symbol	Function
1	VCC	Power supply input: 2.8 – 5.2V
2	GND	Ground
3	SCL	This is the serial clock input
4	SDA	This is a serial data input

27.3

19.26±0.2

12.06(VA)

10.86(AA)

4.02

1.84

2.44

0.3

1.38

2.48

26.7±0.2

23.94(VA)

21.74(AA)

27.3

Active Area 0.96"
128 x 64 Pixels

1 VCC GND SCL SDA 4

Segment 127
(Column 1)

Segment 0
(Column 128)

Common 32
(Row 63)

Common 63
(Row 1)

Common 0
(Row 64)

Common 31
(Row 2)

SCALE 1/1

1.5

6

2

P2.54*(4−1)=7.62

Remove
tape

Component area

1.5(MAX)

1

2.37

23.2±0.1

2.05

3.3

9.84

(P0.7*29=20.3)

20.7±0.1

1.65

(3.5)

4

0.17

0.148

0.148

0.17

DOT SIZE
SCALE 20/1

The non-specified tolerance of dimension is ±0.3 mm .

PIN No.	SYMBOL
1	VCC
2	GND
3	SCL
4	SDA
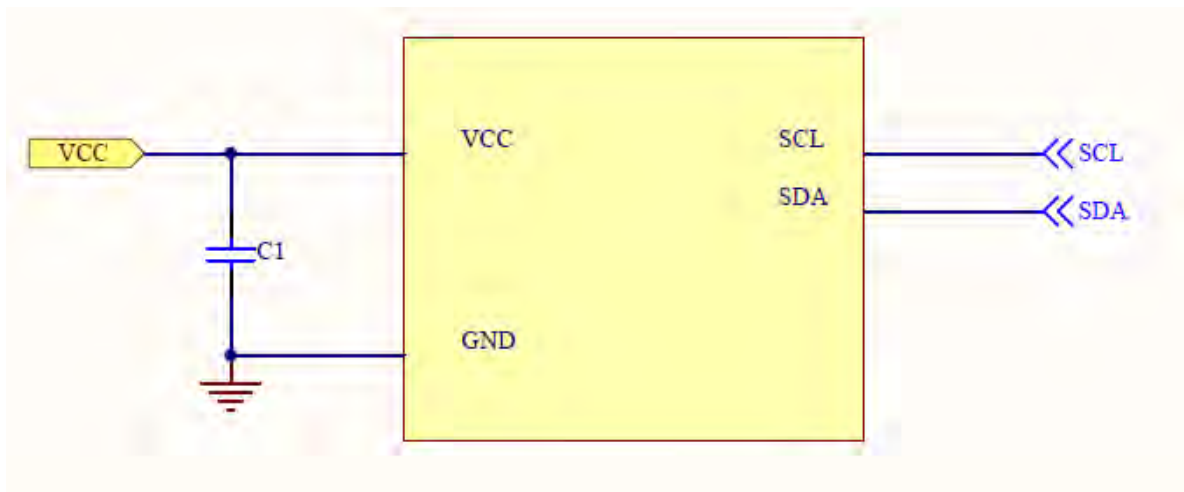
Application recommendations

C1: 1.0uF (1)

Note
(1) The capacitor value is recommended value. Select appropriate value against module application.

Absolute Maximum Ratings

Parameter	Symbol	Min	Max	Unit	Notes
Supply Voltage for Logic	VCC	1.65	5.5	V	1,2
Operating Temperature	TOP	-40	+80	°C	—
Storage Temperature	TSTG	-40	+85	°C	—

Note 1: All the above voltages are on the basis of "VSS = 0V".

Note 2: When this module is used beyond the above absolute maximum ratings, permanent breakage of the module may occur. Also, for normal operations, it is desirable to use this module under the conditions according to Section 6."Optics & Electrical Characteristics". If this module is used beyond these conditions, malfunctioning of the module can occur and the reliability of the module may deteriorate.

Electrical Characteristics

DC Electrical Characteristics

Item	Symbol	Condition	Min	Typ	Max	Unit
Supply Voltage for Logic	VCC	—	2.8	3.3	5.2	V
Input High Volt.	VIH	—	0.8×VCC	—	VCC	V
Input Low Volt.	VIL	—	0	—	0.2×VCC	V
Output High Volt.	VOH	—	0.9×VCC	—	VCC	V
Output Low Volt.	VOL	—	0	—	0.1×VCC	V
50% Check Board operating Current	ICC	Vcc=3.3V	—	14.0	22.0	mA

Initial code

```
Void init_SSD1306BZ(void){

    Write_command(0xAE);    // Display Off

    Write_command(0xD5);    //SET DISPLAY CLOCK
    Write_command(0x80);    //105HZ

    Write_command(0xA8);    // Select Multiplex Ratio
    Write_command(Duty);        // Default => 0~0x3F (1/64 Duty)

    Write_command(0xD3);    //Setting Display Offset
    Write_command(0x00);    //00H Reset,    set common start

    Write_command(0x40);    //Set Display Start Line

    Write_command(0x8D);    // Set Charge Pump
    Write_command(0x14);    // Endable Charge Pump

    Write_command(0xA1);            //Set Segment Re-Map Default
                    //0xA0 (0x00) => column Address 0 mapped to 127
                    //0xA1 (0x01) => Column Address 127 mapped to 0

    Write_command(0xC8);    //Set COM Output Scan Direction

    Write_command(0xDA);    //Set COM Hardware Configuration
    Write_command(0x12);    //Alternative COM Pin---See IC Spec page 34

    Write_command(0x81);    //Set Contrast Control
    Write_command(Contrast_volue);

    Write_command(0xD9);    //Set Pre-Charge period
    Write_command(0x22);

    Write_command(0xDB);    //Set Deselect Vcomh level
    Write_command(0x30);     //

    Write_command(0xA4);    //Entire Display ON

    Write_command(0xA6);    //Set Normal Display
    Write_command(0xAF);    // Display ON

}
```
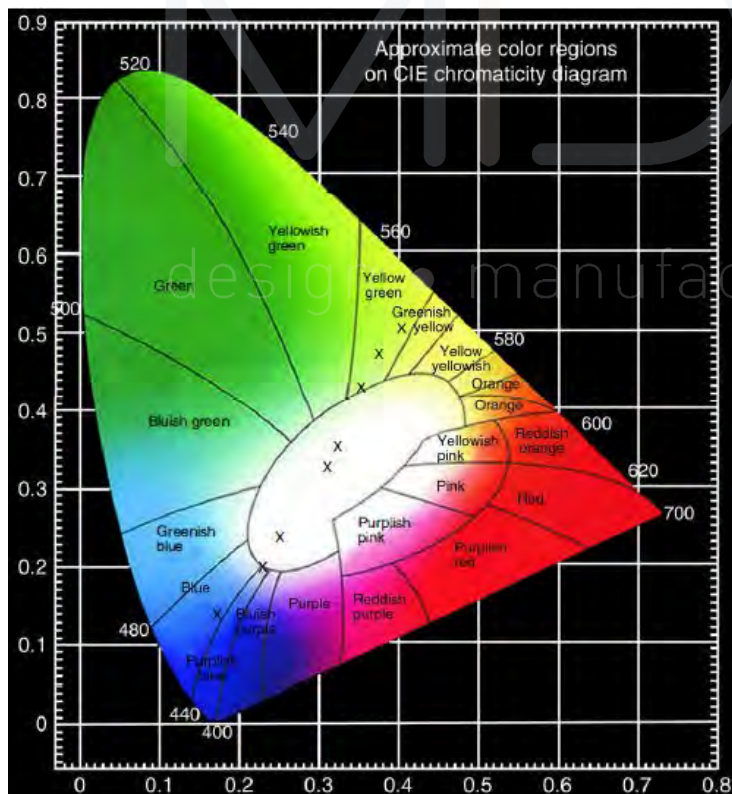
Optical Characteristics

Item	Symbol	Condition	Min	Typ	Max	Unit
View Angle	(V)θ	—	160	—	—	deg
	(H)φ	—	160	—	—	deg
Contrast Ratio	CR	Dark	2000:1	—	—	—
Response Time	T rise	—	—	10	—	μs
	T fall	—	—	10	—	μs
Display with 50% check Board Brightness			60	80	—	cd/m2
CIEx(Yellow)		(CIE1931)	0.45	0.47	0.49	—
CIEy(Yellow)		(CIE1931)	0.48	0.50	0.52	—

OLED Lifetime

ITEM	Conditions	Min	Typ	Remark
Operating Life Time	Ta=25°C / Initial 50% check board brightness Typical Value	50,000 Hrs	-	Note

Notes:
1. Life time is defined the amount of time when the luminance has decayed to <50% of the initial value.
2. This analysis method uses life data obtained under accelerated conditions to extrapolate an estimated probability density function (*pdf*) for the product under normal use conditions.
3. Screen saving mode will extend OLED lifetime.
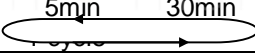
Reliability

Content of Reliability Test

Environmental Test			
Test Item	**Content of Test**	**Test Condition**	**Applicable Standard**
High Temperature storage	Endurance test applying the high storage temperature for a long time.	85°C 240hrs	___
Low Temperature storage	Endurance test applying the low storage temperature for a long time.	-40°C 240hrs	___
High Temperature Operation	Endurance test applying the electric stress (Voltage & Current) and the thermal stress to the element for a long time.	80°C 240hrs	___
Low Temperature Operation	Endurance test applying the electric stress under low temperature for a long time.	-40°C 240hrs	___
High Temperature/ Humidity Storage	Endurance test applying the high temperature and high humidity storage for a long time.	60°C,90%RH 240hrs	___
High Temperature/ Humidity Operation	Endurance test applying the high temperature and high humidity Operation for a long time.	60°C,90%RH 120hrs	___
Temperature Cycle	Endurance test applying the low and high temperature cycle. -40°C 25°C 80°C 30min 5min 30min	-40°C /80°C 30 cycles	___
Mechanical Test			
Vibration test	Endurance test applying the vibration during transportation and using.	Frequency:10~55Hz amplitude:1.5mm Time:0.5hrs/axis Test axis:X,Y,Z	___
Others			
Static electricity test	Endurance test applying the electric stress to the finished product housing.	Air Discharge model ±4kv,10 times	___

*** Supply voltage for OLED system =Operating voltage at 25°C

Test and measurement conditions

1. All measurements shall not be started until the specimens attain to temperature stability. After the completion of the described reliability test, the samples were left at room temperature for 2 hrs prior to conducting the failure test at 23±5°C; 55±15% RH.
2. All-pixels-on is used as operation test pattern.
3. The degradation of Polarizer are ignored for High Temperature storage, High Temperature/ Humidity Storage, Temperature Cycle

Evaluation criteria

1. The function test is OK.
2. No observable defects.
3. Luminance: > 50% of initial value.
4. Current consumption: within ± 50% of initial value.

APPENDIX:

RESIDUE IMAGE

Because the pixels are lighted in different time, the luminance of active pixels
may reduce or differ from inactive pixels. Therefore, the residue image will occur.
To avoid the residue image, every pixel needs to be lighted up uniformly.

Inspection specification
Inspection Standard:
MIL-STD-105E table normal inspection single sample level II.
Definition
1 Major defect : The defect that greatly affect the usability of product.
2 Minor defect : The other defects, such as cosmetic defects, etc.
   Definition of inspection zone:
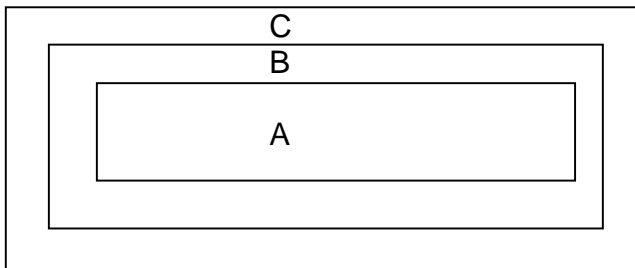
Zone A: Active Area
Zone B: Viewing Area except Zone A
Zone C: Outside Viewing Area
Note: As a general rule, visual defects in Zone C are permissible, when it is no trouble of
     quality and assembly to customer`s product.
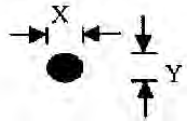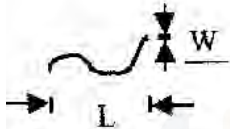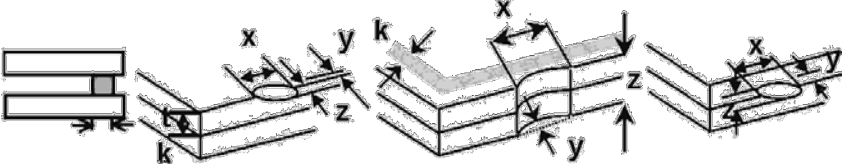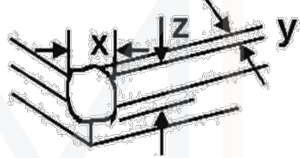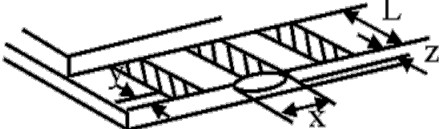
Inspection Methods
1 The general inspection : Under fluorescent light illumination: 750~1500 Lux, about 30cm
 viewing distance, within 45º viewing angle, under 25±5°C.
2 The luminance and color coordinate inspection : By SR-3 or BM-7 or the equal
 equipments, in the dark room, under 25±5°C.
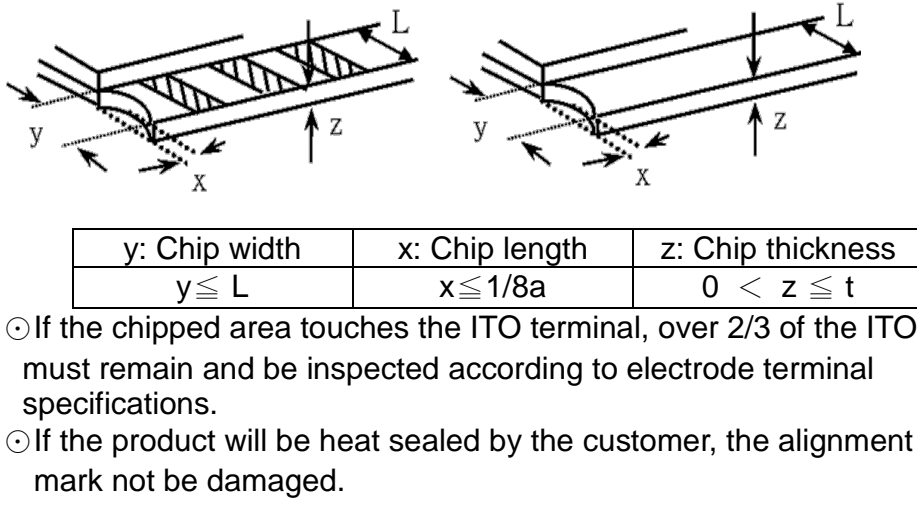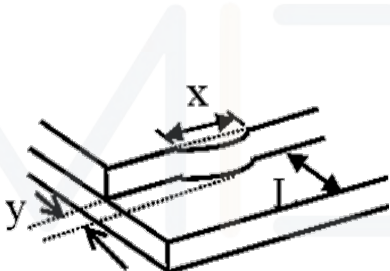
NO	Item	Criterion	AQL
01	Electrical Testing	1.1 Missing vertical, horizontal segment, segment contrast defect. 1.2 Missing character , dot or icon. 1.3 Display malfunction. 1.4 No function or no display. 1.5 Current consumption exceeds product specifications. 1.6 OLED viewing angle defect. 1.7 Mixed product types. 1.8 Contrast defect.	0.65
02	Black or white spots on OLED (display only)	2.1 White and black spots on display ≦0.25mm, no more than three white or black spots present. 2.2 Densely spaced: No more than two spots or lines within 3mm.	2.5

NO	Item	Criterion				AQL
03	OLED black spots, white spots, contamination (non-display)	3.1 Round type : As following drawing $\Phi=(x + y) / 2$				2.5

3.1 Round type table:

SIZE	Acceptable QTY	Zone
$\Phi \leqq 0.10$	Accept no dense	A+ B,
$0.10 < \Phi \leqq 0.20$	2	A+ B
$0.20 < \Phi \leqq 0.25$	1	A+ B
$0.25 < \Phi$	0	A+ B

3.2 Line type : (As following drawing)

Length	Width	Acceptable Q TY	Zone
---	$W \leqq 0.02$	Accept no dense	A+B
$L \leqq 3.0$	$0.02 < W \leqq 0.03$	2	A+B
$L \leqq 2.5$	$0.03 < W \leqq 0.05$		A+B
---	$0.05 < W$	As round type	

(AQL for item 03, 3.2 Line type: 2.5)

NO	Item	Criterion	AQL
04	Polarizer bubbles	If bubbles are visible, judge using black spot specifications, not easy to find, must check in specify direction.	2.5

Size Φ	Acceptable Q TY	Zone
$\Phi \leqq 0.20$	Accept no dense	A+B
$0.20 < \Phi \leqq 0.50$	3	A+B
$0.50 < \Phi \leqq 1.00$	2	A+B
$1.00 < \Phi$	0	A+B
Total Q TY	3	

NO	Item	Criterion	AQL
05	Scratches	Follow NO.3 OLED black spots, white spots, contamination.	

NO	Item	Criterion	AQL
06	Chipped glass	Symbols Define: x: Chip length　　　y: Chip width　　　z: Chip thickness k: Seal width　　　t: Glass thickness　a: OLED side length L: Electrode pad length: 6.1 General glass chip : 6.1.1 Chip on panel surface and crack between panels: | z: Chip thickness	y: Chip width	x: Chip length
---	---	---
Z≦1/2t	Not over viewing area	x≦1/8a
1/2t＜z≦2t	Not exceed 1/3k	x≦1/8a | ⊙If there are 2 or more chips, x is total length of each chip.	2.5
		6.1.2 Corner crack: | z: Chip thickness	y: Chip width	x: Chip length
---	---	---
Z≦1/2t	Not over viewing area	x≦1/8a
1/2t＜z≦2t	Not exceed 1/3k	x≦1/8a | ⊙If there are 2 or more chips, x is the total length of each chip.	2.5
	Glass crack	Symbols : x: Chip length　　　y: Chip width　　　z: Chip thickness k: Seal width　　　t: Glass thickness　a: OLED side length L: Electrode pad length 6.2 Protrusion over terminal : 6.2.1 Chip on electrode pad : | y: Chip width	x: Chip length	z: Chip thickness
---	---	---
y≦0.5mm	x≦1/8a	0 ＜ z ≦ t		2.5
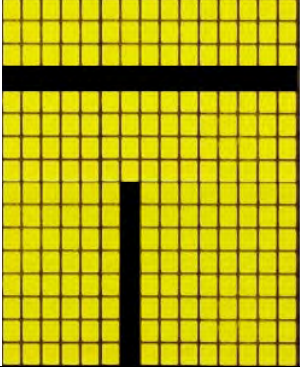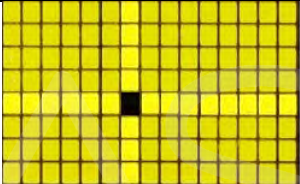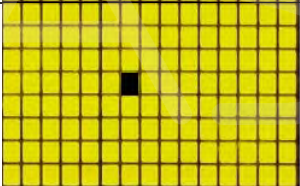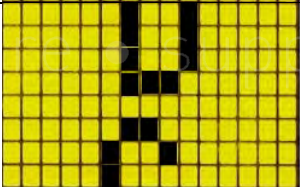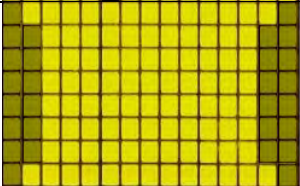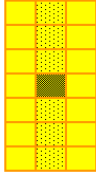
NO	Item	Criterion	AQL
06	Glass crack	6.2.2 Non-conductive portion: | y: Chip width	x: Chip length	z: Chip thickness | |---|---|---| | $y \leq L$ | $x \leq 1/8a$ | $0 < z \leq t$ | ⊙If the chipped area touches the ITO terminal, over 2/3 of the ITO must remain and be inspected according to electrode terminal specifications. ⊙If the product will be heat sealed by the customer, the alignment mark not be damaged. 6.2.3 Substrate protuberance and internal crack. | y: width	x: length | |---|---| | $y \leq 1/3L$ | $x \leq a$ | 	2.5
07	Cracked glass	The OLED with extensive crack is not acceptable.	2.5
08	Backlight elements	8.1 Illumination source flickers when lit. 8.2 Spots or scratched that appear when lit must be judged. Using OLED spot, lines and contamination standards. 8.3 Backlight doesn't light or color wrong.	0.65 2.5 0.65
09	Bezel	9.1 Bezel may not have rust, be deformed or have fingerprints, stains or other contamination. 9.2 Bezel must comply with job specifications.	2.5 0.65

NO	Item	Criterion	AQL
10	PCB , COB	10.1 COB seal may not have pinholes larger than 0.2mm or contamination.	2.5
		10.2 COB seal surface may not have pinholes through to the IC.	2.5
		10.3 The height of the COB should not exceed the height indicated in the assembly diagram.	0.65
		10.4 There may not be more than 2mm of sealant outside the seal area on the PCB. And there should be no more than three places.	2.5
		10.5 No oxidation or contamination PCB terminals.	2.5
		10.6 Parts on PCB must be the same as on the production characteristic chart. There should be no wrong parts, missing parts or excess parts.	0.65
		10.7 The jumper on the PCB should conform to the product characteristic chart.	0.65
		10.8 If solder gets on bezel tab pads, OLED pad, zebra pad or screw hold pad, make sure it is smoothed down.	2.5
11	Soldering	11.1 No un-melted solder paste may be present on the PCB.	2.5
		11.2 No cold solder joints, missing solder connections, oxidation or icicle.	2.5
		11.3 No residue or solder balls on PCB.	2.5
		11.4 No short circuits in components on PCB.	0.65
12	General appearance	12.1 No oxidation, contamination, curves or, bends on interface Pin (OLB) of TCP.	2.5
		12.2 No cracks on interface pin (OLB) of TCP.	0.65
		12.3 No contamination, solder residue or solder balls on product.	2.5
		12.4 The IC on the TCP may not be damaged, circuits.	2.5
		12.5 The uppermost edge of the protective strip on the interface pin must be present or look as if it cause the interface pin to sever.	2.5
		12.6 The residual rosin or tin oil of soldering (component or chip component) is not burned into brown or black color.	2.5
		12.7 Sealant on top of the ITO circuit has not hardened.	2.5
		12.8 Pin type must match type in specification sheet.	0.65
		12.9 OLED pin loose or missing pins.	0.65
		12.10 Product packaging must the same as specified on packaging specification sheet.	0.65
		12.11 Product dimension and structure must conform to product specification sheet.	0.65

Check Item	Classification	Criteria
No Display	Major	
Missing Line	Major	
Pixel Short	Major	
Darker Short	Major	
Wrong Display	Major	
Un-uniform B/A x 100% < 70% A/C x 100% < 70%	Major	A Normal B Dark Pixel C Light Pixel

Precautions in use of OLED Modules

(1) Avoid applying excessive shocks to module or making any alterations or modifications to it.
(2) Don't make extra holes on the printed circuit board, modify its shape or change the components of OLED display module.
(3) Don't disassemble the OLED display module.
(4) Don't operate it above the absolute maximum rating.
(5) Don't drop, bend or twist OLED display module.
(6) Soldering: only to the I/O terminals.
(7) Storage: please storage in anti-static electricity container and clean environment.
(8) It's pretty common to use "Screen Saver" to extend the lifetime and Don't use fix information for long time in real application.
(9) Don't use fixed information in OLED panel for long time, that will extend "screen burn" effect time..
(10) MIDAS has the right to change the passive components, including R2and R3 adjust resistors.   (Resistors, capacitors and other passive components will have different appearance and color caused by the different supplier.)
(11) MIDAS have the right to change the PCB Rev. (In order to satisfy the supplying stability, management optimization and the best product performance...etc, under the premise of not affecting the electrical characteristics and external dimensions, MIDAS have the right to modify the version.)

Handling Precautions

(1) Since the display panel is being made of glass, do not apply mechanical impacts such us dropping from a high position.
(2) If the display panel is broken by some accident and the internal organic substance leaks out, be careful not to inhale nor lick the organic substance.
(3) If pressure is applied to the display surface or its neighborhood of the OLED display module, the cell structure may be damaged and be careful not to apply pressure to these sections.
(4) The polarizer covering the surface of the OLED display module is soft and easily scratched. Please be careful when handling the OLED display module.
(5) When the surface of the polarizer of the OLED display module has soil, clean the surface. It takes advantage of by using following adhesion tape.
* Scotch Mending Tape No. 810 or an equivalent
Never try to breathe upon the soiled surface nor wipe the surface using cloth containing solvent
Also, pay attention that the following liquid and solvent may spoil the polarizer:
* Water
* Ketone
* Aromatic Solvents
(6) Hold OLED display module very carefully when placing OLED display module into the System housing. Do not apply excessive stress or pressure to OLED display module. And, do not over bend the film with electrode pattern layouts. These stresses will influence the display performance. Also, secure sufficient rigidity for the outer cases.
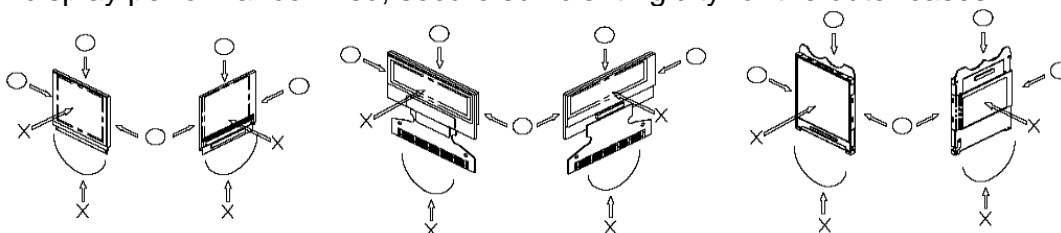
(7) Do not apply stress to the LSI chips and the surrounding molded sections.
(8) Do not disassemble nor modify the OLED display module.
(9) Do not apply input signals while the logic power is off.
(10) Pay sufficient attention to the working environments when handing OLED display modules to prevent occurrence of element breakage accidents by static electricity.
* Be sure to make human body grounding when handling OLED display modules.
* Be sure to ground tools to use or assembly such as soldering irons.
* To suppress generation of static electricity, avoid carrying out assembly work under dry environments.
* Protective film is being applied to the surface of the display panel of the OLED display module. Be careful since static electricity may be generated when exfoliating the protective film.
(11) Protection film is being applied to the surface of the display panel and removes the protection film before assembling it. At this time, if the OLED display module has been stored surface of the display panel after removed of the film. In such case, remove the residue material by the method introduced in the above Section 5.
(12) If electric current is applied when the OLED display module is being dewed or when it is placed under high humidity environments, the electrodes may be corroded and be careful to avoid the above.

Storage Precautions
(1) When storing OLED display modules, put them in static electricity preventive bags avoiding exposure to direct sun light nor to lights of fluorescent lamps. And, also, avoiding high temperature and high humidity environment or low temperature (less than 0°C) environments.(We recommend you to store these modules in the packaged state when they were shipped from MIDAS. At that time, be careful not to let water drops adhere to the packages or bags nor let dewing occur with them.
(2) If electric current is applied when water drops are adhering to the surface of the OLED display module, when the OLED display module is being dewed or when it is placed under high humidity environments, the electrodes may be corroded and be careful about the above.

Designing Precautions
(1) The absolute maximum ratings are the ratings which cannot be exceeded for OLED display module, and if these values are exceeded, panel damage may be happen.
(2) To prevent occurrence of malfunctioning by noise, pay attention to satisfy the VIL and VIH specifications and, at the same time, to make the signal line cable as short as possible.
(3)   e recommend you to install excess current preventive unit (fuses, etc.) to the power circuit (VDD). (Recommend value: 0.5A)
(4) Pay sufficient attention to avoid occurrence of mutual noise interference with the neighboring devices.
(5) As for EMI, take necessary measures on the equipment side basically.
(6) When fastening the OLED display module, fasten the external plastic housing section.
(7) If power supply to the OLED display module is forcibly shut down by such errors as taking out the main battery while the OLED display panel is in operation, we cannot guarantee the quality of this OLED display module. Connection (contact) to any other potential than the above may lead to rupture of the IC.